

Docket No.: 312302US40PCT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION: Hui ZHONG, et al.

SERIAL NO.: 10/049,270

GAU: 2841

FILED: June 27, 2002

EXAMINER: Tuan T. DINH

FOR: MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION,
METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND
SEMICONDUCTOR DEVICE

LETTER SUBMITTING REPLACEMENT DRAWING SHEET(S)

COMMISSIONER FOR PATENTS
Alexandria, VA 22313

SIR:

Responsive to the below indicated communication, the following drawing sheets are submitted herewith:

☒ **1 Replacement Drawing Sheets** ☐ _____ New Drawing Sheets

☐ _____ Annotated Drawing Sheets

☒ **Official Action dated November 5, 2007**

☐ Notice of Allowance/Issue Fee dated _____

☐ Other dated _____

The changes and/or modifications made include the following:

A detailed view of the solder resist layer 14 as described in the specification has been added.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Customer Number

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Richard D. Kelly
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A handwritten signature in black ink, appearing to read "E. Garlepp".

Edwin D. Garlepp
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